



Qualification

**501-51068**

Test Report

PRE: Christine Goh

30<sup>th</sup> Jun 11

Rev.C

APP: Justin Goh

DCR No.  
D20110629222016\_481520

---

Title: SLIMLINE Serial ATA (SATA) Connector, Plug

**Design Objective:** 108-51075 Rev C

**Test Request No.:** T06 - 113

**Date:** 30<sup>th</sup> Jun 2011

**Classification:** Unrestricted

**Prepared by:** Christine Goh

This report remains the property of Tyco Electronics Manufacturing (S) Pte Ltd and cannot be reproduced without the written consent of Tyco Electronics Manufacturing (S) Pte Ltd.

---

	<u>Table of Contents</u>	<u>Page</u>
1.	Introduction	3
1.1	Purpose	3
1.2	Scope	3
1.3	Conclusion	3
1.4	Product Description	3
1.5	Test Samples	3
1.6	Qualification Test Sequence	4
2.	Summary of Testing	5
2.1	Examination of Product	5
2.2	Termination Resistance	5 ~ 6
2.3	Mating & Un-mating	7
2.4	Insulation Resistance	7
2.5	Dielectric Withstanding Voltage	7
2.6	Vibration & Physical shock	7
2.7	Solder Ability	7
2.8	Resistance to Soldering Heat	8
2.9	Durability	8
2.10	Mixed Flowing Gas	8
2.11	Temperature rise	8
3.	Test Methods	9
3.1	Examination of Product	9
3.2	Insulation Resistance	9
3.3	Dielectric Withstanding Voltage	9
3.4	Contact / Termination Resistance	9
3.5	Durability	9
3.6	Humidity (Steady)	9
3.7	Thermal Shock	9
3.8	Vibration (Random)	9
3.9	Physical Shock	9
3.10	Temperature Life	10
3.11	Mating Force	10
3.12	Un-mating Force	10
3.13	Solder Ability	10
3.14	Resistance to Soldering Heat	10
3.15	Temperature rise	10
3.16	Mixed Flowing Gas	10

---

## Qualification Test Report

### 1. Introduction

#### 1.1 Purpose

Testing was performed on Slimline Serial ATA (SATA) Plug connector, so as to determine its conformance to the requirements of Design Objectives 108-51075 Rev C.

#### 1.2 Scope

This report covers the electrical, mechanical and environmental performance of, Slimline Serial ATA (SATA) Plug connector manufactured by Tyco Electronics Manufacturing (S) Pte Ltd.

#### 1.3 Conclusion

The Slimline Serial ATA (SATA) Plug connector meets all the electrical, mechanical and environmental requirements of Design Objectives 108-51075 Rev C.

#### 1.4 Product Description

The Slimline Serial ATA (SATA) Plug connector, housing material is made of high temperature thermoplastics, glass filled, UL94V-0. The contacts are made of Brass strip. Contacts finish were Gold plating at mating area and Tin plating at solder area. All over nickel underplate.

#### 1.5 Test Samples

The test samples used for the qualification were randomly selected from production and the conditions of the parts used for each test were summarized in the table below:

Description	Part No.
Slimline Serial ATA (SATA) Connector, Plug, 7P+6P	1735418, 1735419, 1735420, 1735424, 1735471, 1735574

## 1.6 Qualification Test Sequence

Test Item	Test Group						
	1	2	3	4	5	6	7
	Test Sequence (a)						
Examination of Product	1,5	1,9	1,8	1,8	1,7	1,5	1,3
Low Level Contact Resistance	2,4	3,7	2,4, 6		4,6	2,4	
Insulation Resistance				2,6			
Dielectric Withstanding Voltage				3,7			
Current Rating			7				
Solder Ability							2
Soldering Heat Resistivity						3	
Mating Force		2					
Un-mating Force		8					
Durability	3	4(b)			2(b)		
Vibration(Random)		5					
Physical Shock		6					
Reseating (Manually plug/unplug 3 time)			5		5		
Humidity				5			
Temperature Life			3				
Thermal Shock				4			
Mixed Flowing Gas					3		

**NOTE:**

- (a) Numbers indicate sequence in which the tests are performed.
- (b) Preconditioning, 20 cycles for the 50 durability cycle requirement, 50 cycles for the 500 durability cycle requirement. The mating and Un-mating cycle is at the maximum rate of 200 cycles per hour.

## 2. Summary of Testing

### 2.1 Examination of Product – All Groups

All samples were visually inspected under the scope and found to be free from any physical damages such as cracks, change of colour, corrosion etc.

### 2.2 Termination Resistance - Test Group 1, 2, 3, 5 & 6

All samples meet the requirement of 30 mΩ (maximum) initial termination resistance. All samples meet the requirement of ΔR 15 mΩ (maximum) after test / environmental conditions.

All Termination Resistance Measurement in mΩ

Test Group (TG)	1 (Durability)	
Test Condition	Initial	After
Sample size	5	5
No. of measurement	65	65
Overall average	17.21	17.58
Overall minimum	14.86	14.42
Overall maximum	20.09	23.35
ΔR (max)	-	4.78

Test Group (TG)	2 (Vibration & Physical Shock)	
Test Condition	Initial	After Physical Shock
Sample size	5	5
No. of measurement	65	65
Overall average	16.51	16.50
Overall minimum	14.02	14.17
Overall maximum	19.05	19.33
ΔR (max)	-	1.27

Test Group (TG)	3 (Temperature Life)		
Test Condition	Initial	After Temperature Life	After Reseating
Sample size	5	5	5
No. of measurement	65	65	65
Overall average	17.11	18.95	18.56
Overall minimum	14.73	15.69	15.23
Overall maximum	19.96	25.67	26.56
$\Delta R$ (max)	-	6.79	6.83

Test Group (TG)	5 (Mixed Flowing Gas - MFG)			
Sample Condition	Group A		Group B	
	Mated for 14 days		Unmated for 7 days, mated for additional 7 days	
Test Condition	After MFG	After Reseating	After MFG	After Reseating
Sample size	5	5	5	5
No. of measurement	65	65	65	65
Overall average	17.82	17.87	17.96	17.73
Overall minimum	15.04	14.98	14.73	14.50
Overall maximum	24.53	23.39	24.63	23.18
$\Delta R$ (max)	4.82	3.68	6.04	3.14

Test Group (TG)	6 (Soldering Heat Resistivity)	
Test Condition	Initial	After
Sample size	5	5
No. of measurement	65	65
Overall average	17.27	17.00
Overall minimum	14.79	15.13
Overall maximum	19.84	20.93
$\Delta R$ (max)	-	1.39

### 2.3 Mating & Un-mating – Test Group 2

The mating force meets the requirement of 2.0kgf (Max).

The un-mating force meets the requirement of 0.25kgf (Min) after 500 cycle of durability.

All force measurements in Kgf.

Test Group (TG)	2	
Test Condition	1st Cycle Mating	Final Cycle Un-mating
Sample size	5	5
Number of measurement	5	5
Average	0.416	0.299
Minimum	0.362	0.262
Maximum	0.443	0.340

### 2.4 Insulation Resistance – Test Group 4

All insulation resistance readings between adjacent contacts were greater than 1000M $\Omega$  (initial & final).

Test Group (TG)	4 (Thermal Shock & Humidity )	
Sample Condition	Un-mated	
Test Condition	Initial	After Humidity
Sample size	5	5
Number of measurement	55	55
Average	2.45E+14	7.99E+13
Minimum	1.02E+14	1.03E+13
Maximum	9.86E+14	4.04E+14

### 2.5 Dielectric Withstanding Voltage – Test Group 4

No dielectric breakdown or flashover or leakage of current greater than 5mA occurred when a test voltage of 500 VAC was applied between adjacent contacts of unmated connector assemblies.

### 2.6 Vibration & Physical Shock - Test Group 2

No Sample failed the electrical discontinuity.

### 2.7 Solder Ability – Test Group 7

All contact leads showed more than 95% solder coverage with no voids and pins hole observed.

**2.8 Soldering Heat Resistivity– Test Group 6**

No physical damage was observed after reflow.

**2.9 Durability – Test Group 1, 2 & 5**

No physical damage was observed after durability.

**2.10 Mixed Flowing Gas – Test Group 5**

No physical damage was observed after mixed flowing gas.

**2.11 Temperature rise – Test Group 3**

Temperature rise meets the requirement of less than 30°C

Sample size	5
No. of measurement	20
Overall average	10.28
Overall minimum	7.35
Overall maximum	12.79

---

### **3 Test Methods**

#### **3.1 Examination of Products**

Samples were physically examined under the microscope before and after each test conditions for any physical damage or abnormalities on housing and contacts.

#### **3.2 Insulation Resistance**

Insulation resistance was measured between adjacent contacts of connector, using a test voltage of 500 VDC. Record reading after 1 minute. (EIA-364-21)

#### **3.3 Dielectric Withstanding Voltage**

A test potential of 500 VDC was applied between adjacent contacts of connector. This potential was held for 1 minute with a current leakage not greater than 5mA. (EIA-364-20, Method B)

#### **3.4 Contact/Termination Resistance**

Measurements shall be made on mated connector, at a voltage of 20mv max open circuit at a current of 100mA. (EIA-364-23)

#### **3.5 Durability**

Subject connector to 500 cycles of repeated mate and un-mate, with an operation speed of 12.5mm per minute. (EIA-364-09)

#### **3.6 Humidity (Steady)**

Subject mated connectors to relative humidity of 90~95%RH, temperature of  $40\pm 2^{\circ}\text{C}$  for 96 hours. (EIA-364-31, Method II, Condition A)

#### **3.7 Thermal Shock**

Subjected mated connectors to temperature  $-55^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  for 10 cycles, each temperature dwell time 30 minutes. (EIA-364-32, Condition I)

#### **3.8 Vibration (Random)**

Subject mated connectors for 30 minutes in each of 3 mutually perpendicular planes. Frequency of 50 ~ 2000Hz with 5.35 g's RMS. (EIA-364-28, Condition V, Letter A)

#### **3.9 Physical Shock**

Subject mated connector to 50Gs half sine pulses of 11ms duration along the 3 mutually perpendicular planes. (EIA-364-27, Condition H)

---

**3.10 Temperature Life**

Subject mated connector to  $85\pm 2^{\circ}\text{C}$  for 500 hours. (EIA-364-17, Method A, Condition III)

**3.11 Mating Force**

Mate connector assembly at a rate of 12.5mm per minute.

**3.12 Un-mating Force**

Un-mate connector assembly at a rate 12.5mm per minute.

**3.13 Solder Ability**

Immerse solderable portion of contact in molten solder at  $245^{\circ}\text{C}$  for 5 seconds.

**3.14 Resistance to Soldering Heat**

Test connector per EIA-364-56B, procedure 6, level 4.

**3.15 Current Rating**

Wire contact P2 & P3 in parallel for power. Wire contact P5 & P6 in parallel for return.

Apply 3A total DC current to parallel contacts P2 & P3 and return from parallel contact P5 & P6.

**3.16 Mixed Flowing Gas**

Expose half of samples un-mated for 7 days then mated for 7 additional days and expose other half of samples mated 14 days. (EIA-364-65, Class 2A)